

PRODUCT CHARACTERISTICS

V_{DS}	650V
$R_{DS(ON)}$ Typ(@ $V_{GS}=10V$)	0.35 Ω
Qg@typ	20.6nC
I_D	11A

APPLICATIONS

- * High efficiency switch mode power supplies
- * Electronic lamp ballasts based on half bridge
- * LED power supplies

FEATURE

- * High Switching Speed
- * Improved dv/dt capability

ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
MOT65R380G	N/A	PDFN5X6	5000 pieces/Reel

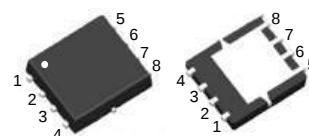
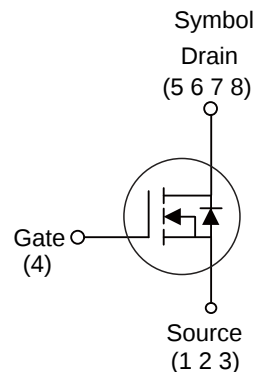
ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current Continuous(@ $V_{GS}=10V$, $T_C=25^{\circ}C$)	I_D	11	A
Drain Current Pulsed	I_{DM}	44	A
Avalanche Energy *	E_{AS}	160	mJ
Peak Diode Recovery dv/dt	dv/dt	5.0	V/ns
Power Dissipation	P_D	118	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	1.06	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C$, $V_{DS}=50V$, $V_G=10V$, $L=20mH$, $R_g=25\Omega$



PDFN5X6



■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V _{DSS}	V _{GS} =0V, I _D =250μA	650	-	-	V
Drain to Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	-	-	1	μA
Gate to Source Forward Leakage	I _{GSS(F)}	V _{DS} =0V, V _{GS} =+30V	-	-	100	nA
Gate to Source Reverse Leakage	I _{GSS(R)}	V _{DS} =0V, V _{GS} =-30V	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5.5A	-	0.35	0.38	Ω
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.5	-	4.5	V
Dynamic characteristics						
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V ,f=1.0MHz	-	5.98	-	Ω
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =5.5A	5	-	-	S
Input Capacitance	C _{iss}	V _{DS} =40V, V _{GS} =0V f=1.0MHz	-	872	-	pF
Output Capacitance	C _{oss}		-	198	-	pF
Reverse Transfer Capacitance	C _{rss}		-	4.1	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	t _{d(ON)}	I _D =5.5 A, V _{DS} =400V R _G =10 Ω ,V _{GS} =10V	-	46.8	-	ns
Rise Time	t _r		-	10.6	-	ns
Turn-off Delay Time	t _{d(OFF)}		-	40.2	-	ns
Fall Time	t _f		-	7.0	-	ns
Total Gate Charge	Q _g	I _D =5.5 A, V _{DS} =520V V _{GS} =10V	-	20.6	-	nC
Gate to Source Charge	Q _{gs}		-	4.6	-	nC
Gate to Drain("Miller") Charge	Q _{gd}		-	5.8	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I _s		-	-	11	A
Maximum Pulsed Current(Body Diode)	I _{SM}		-	-	44	A
Diode Forward Voltage	V _{SD}	I _{SD} =5.5A, V _{GS} =0V	-	0.81	1.2	V
Reverse Recovery Time	t _{rr}	I _{SD} =5.5A, T _J =25℃	-	240	-	ns
Reverse Recovery Charge	Q _{rr}	dI /dt=100A/μs	-	1963	-	nC

■ TYPICAL CHARACTERISTICS

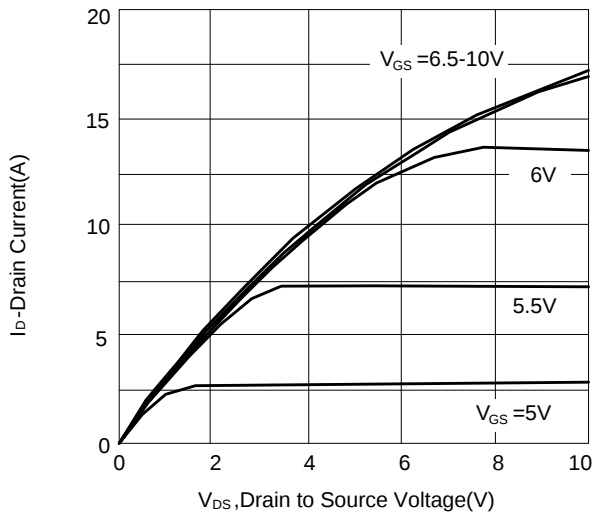


Figure 1: Output Characteristics

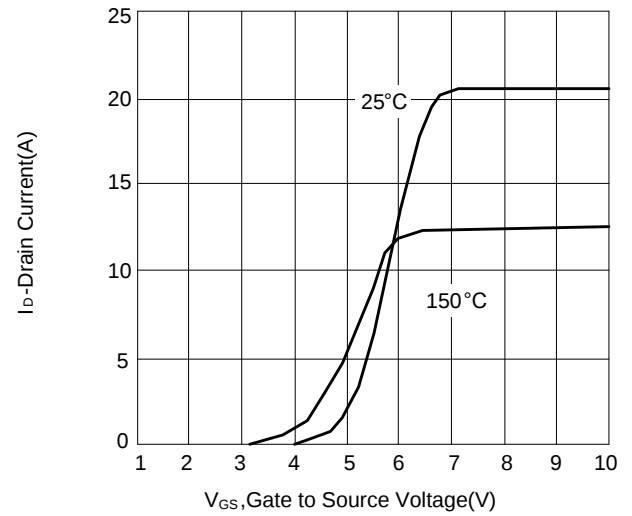


Figure 2: Transfer Characteristics

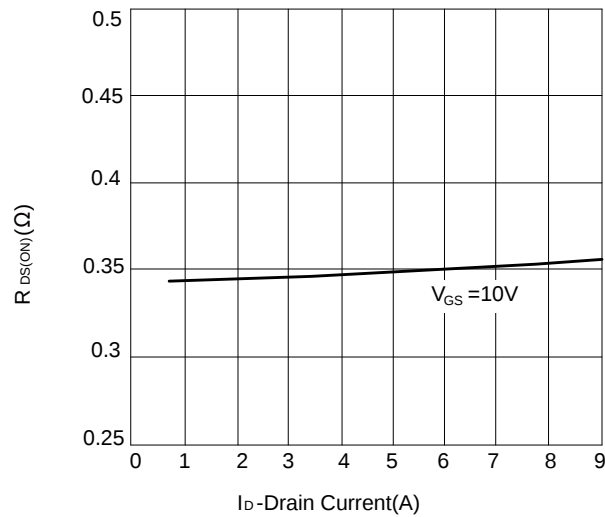


Figure 3: Drain to Source On-Resistance vs. Drain Current

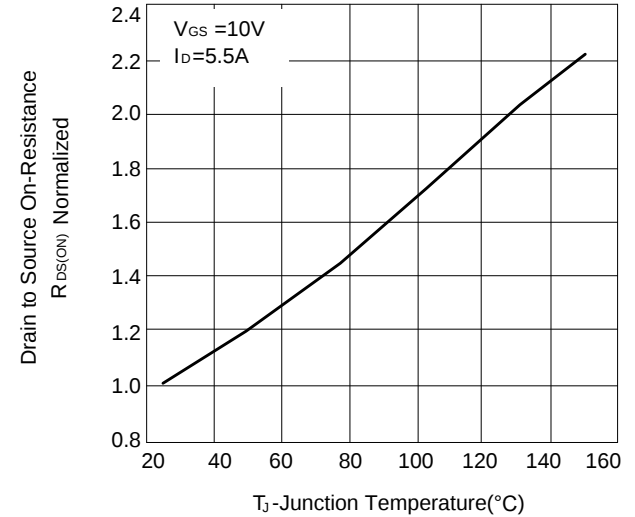


Figure 4: Drain to Source On-Resistance vs. Junction Temperature

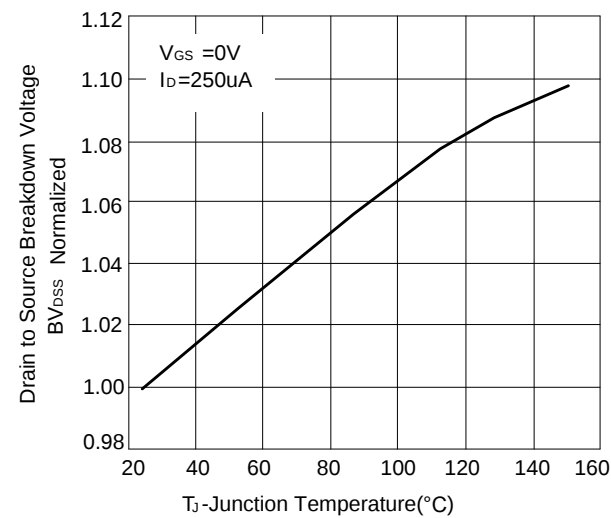


Figure 5: Breakdown Voltage vs. Junction Temperature

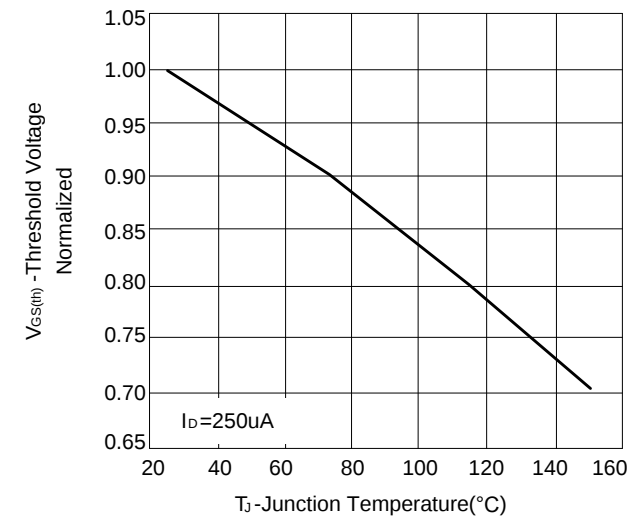


Figure 6: Threshold Voltage vs. Junction Temperature

■ TYPICAL CHARACTERISTICS(Cont.)

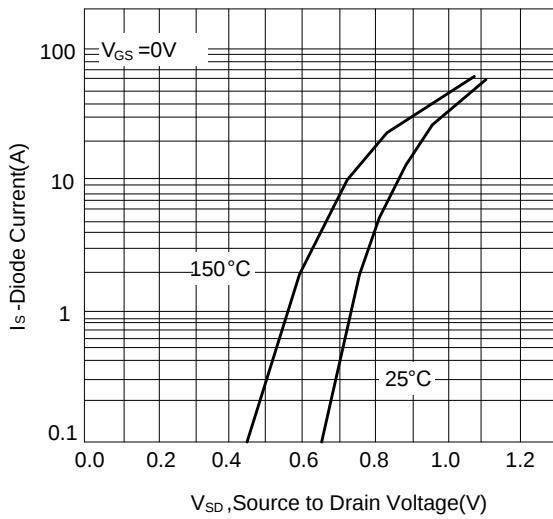


Figure 7: Body Diode Characteristics

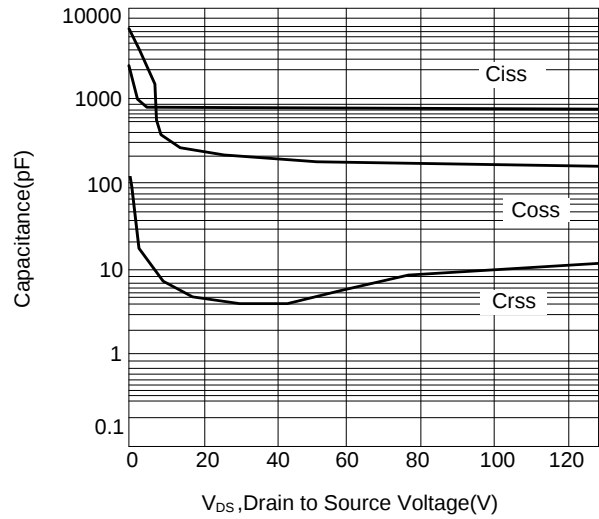


Figure 8: Capacitance vs Drain to Source Voltage

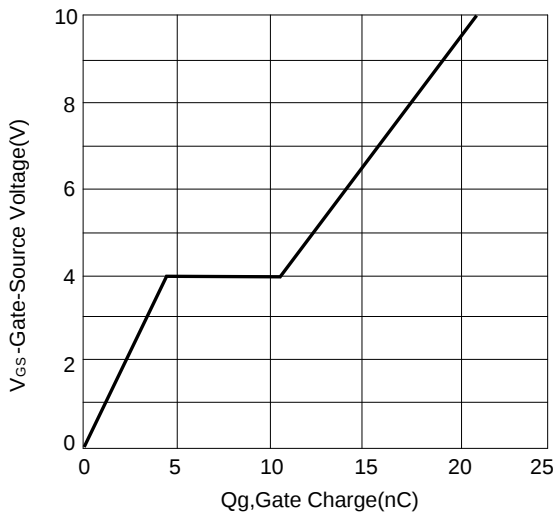


Figure 9: Gate Charge vs Gate to Source Voltage

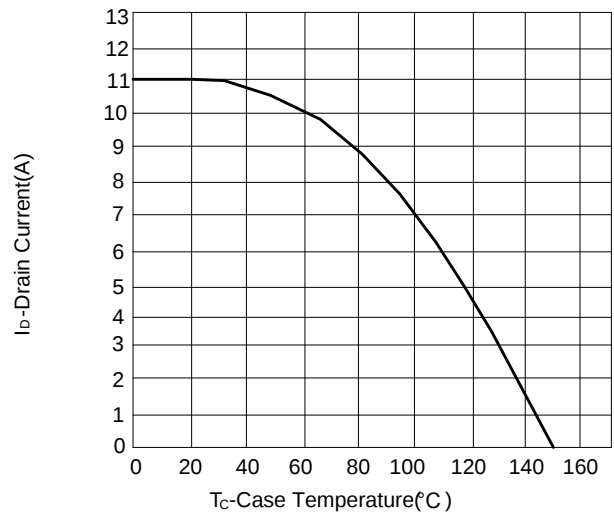


Figure 10: Continuous Drain vs Case Temperature

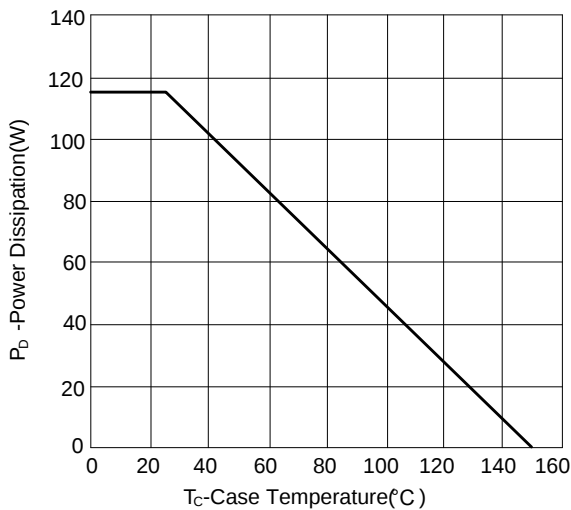


Figure 11: Power Dissipation vs Case Temperature

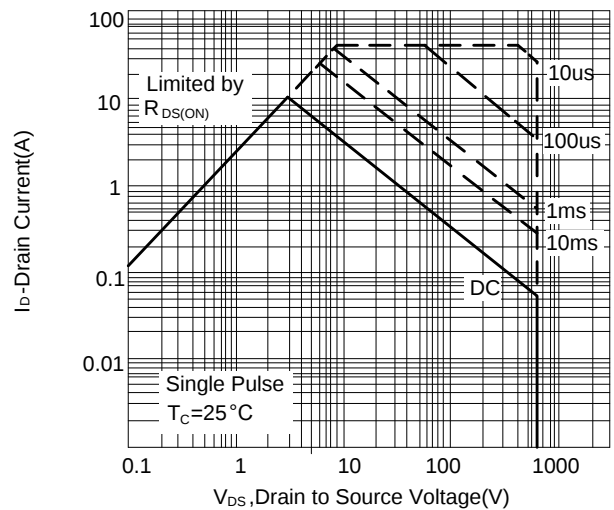
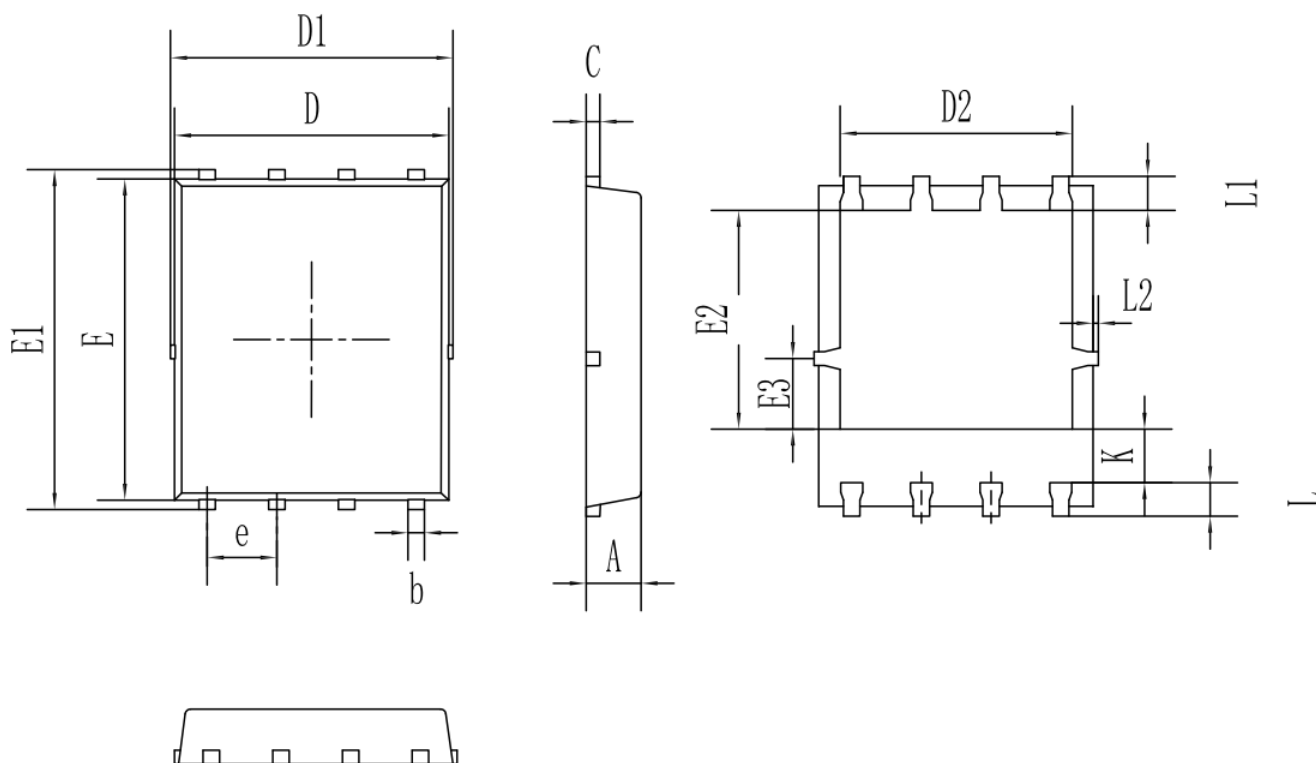
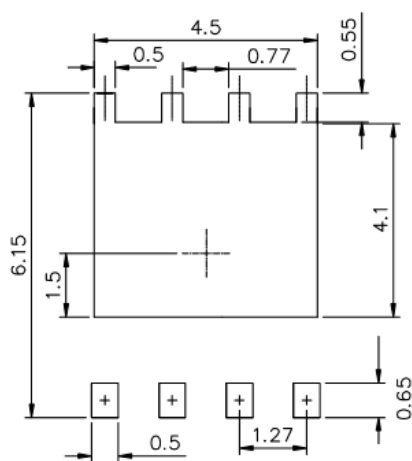


Figure 12: Safe operating Area

■ PDFN5X6 PACKAGE OUTLINE DIMENSIONS



RECOMMENDED LAND PATTERN



UNIT:mm

	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.25	0.35	0.50
c	0.10	0.20	0.30
D	4.80	5.00	5.20
D1	4.90	5.10	5.30
D2	3.92	4.02	4.20
E	5.65	5.75	5.85
E1	5.95	6.10	6.25
E2	3.325	3.525	3.775
E3	0.80	0.90	1.00
e		1.27	
L	0.40	0.55	0.70
L1		0.65	
L2	0.00		0.15
K	1.00	1.30	1.50

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